



SOT1574-3

plastic, thermally enhanced quad flat non-leaded package; 16 terminals; 1.0 mm pitch; 6 mm x 6 mm x 1.98 mm body

26 February 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HQFN16
Package style descriptive code	HQFN (thermal enhanced quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	26-07-2017
Manufacturer package code	98ASA00690D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	6	-	mm
package width	-	6	-	mm
seated height	1.93	1.98	2.03	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	16	-	



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2 Package outline

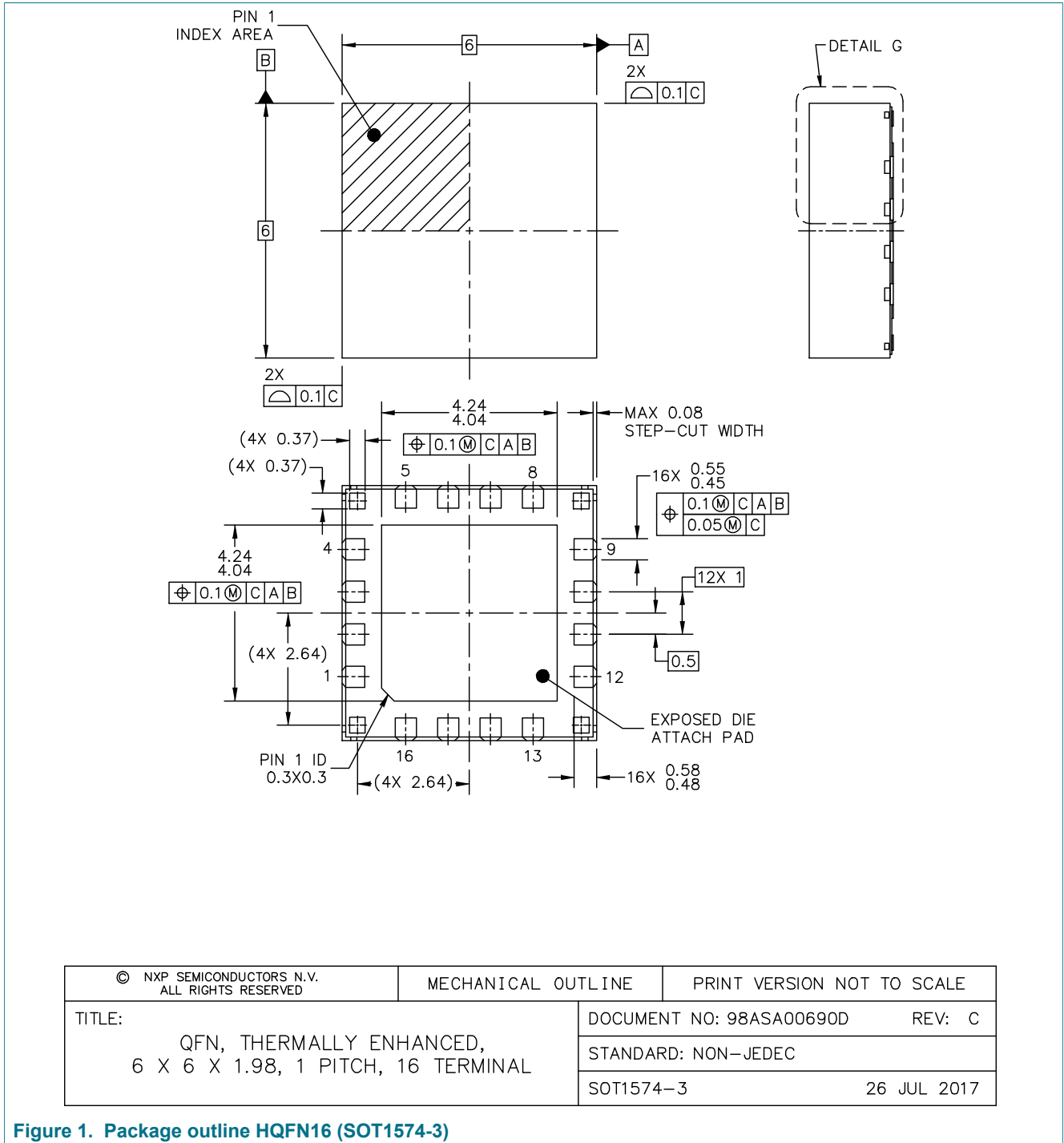
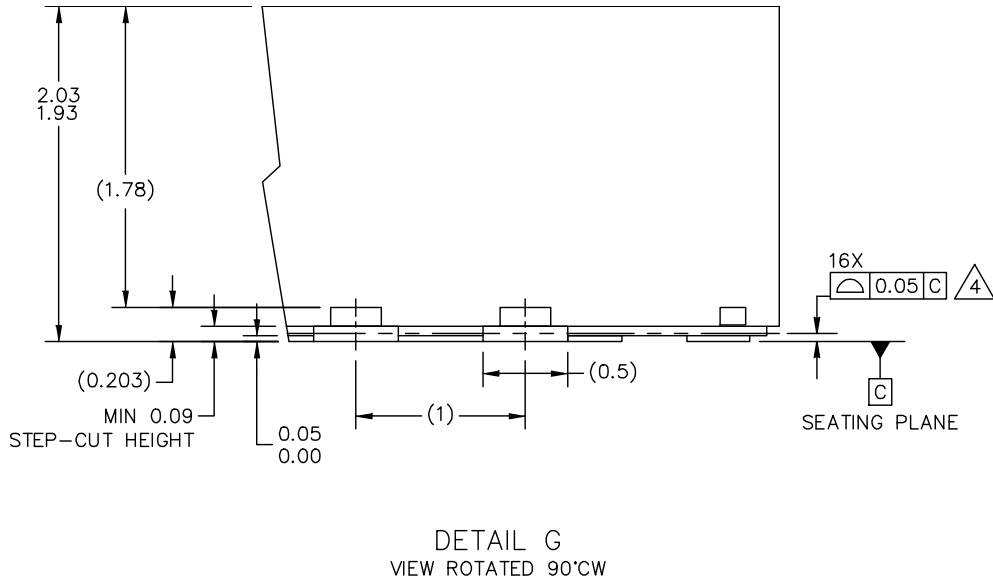


Figure 1. Package outline HQFN16 (SOT1574-3)

plastic, thermally enhanced quad flat non-leaded package; 16 terminals; 1.0 mm pitch; 6 mm x 6 mm x 1.98 mm body




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TITLE: QFN, THERMALLY ENHANCED, 6 X 6 X 1.98, 1 PITCH, 16 TERMINAL		DOCUMENT NO: 98ASA00690D	REV: C
		STANDARD: NON-JEDEC	
		SOT1574-3	26 JUL 2017

Figure 2. Package outline dt1 HQFN16 (sot1574-3)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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Figure 3. Package outline note HQFN16 (sot1574-3)

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3 Legal information

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